

Product Change Notification - RMES-24CGNQ027

Date:

26 Apr 2019

Product Category:

8-bit Microcontrollers

Affected CPNs:



Notification subject:

CCB 3676 Final Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L DFN (4x4x0.9mm) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and).

Description of Change:

Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L DFN (4x4x0.9mm) package.

Pre Change:

Assembled at NSEB using 8600 die attach material

Post Change:

Assembled at NSEB using 8600 die attach material or Assembled at MMT using 3280 die attach material

Pre and Post Change Summary:

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	Pre Change	hange	
Assembly Site	UTAC Thai Limited (UTL-1) LTD. / NSEB	UTAC Thai Limited (UTL-1) LTD./ NSEB	Microchip (Branch) / MMT
Wire material	Au	Au	Au
Die attach material	8600	8600	3280
Lead frame Material	A194	A194	A194
Molding compound material	G700LTD	G700LTD	G700LTD

Impacts to Data Sheet:

None

Reason for Change:

To improve productivity and on-time delivery performance by MMT as an additional assembly site.

Estimated First Ship Date:

May 26, 2019 (date code: 1922)

NOTE: Please be advised that after the estimated first ship may receive pre and post change parts.

Time Table Summary:



	February 2019			>	April 2019			May 2019							
Workweek	05	06	07	80	09	/	14	15	16	17	18	19	20	21	22
Initial PCN Issue		V													
Date		^													
Report Availability										Χ					
Final PCN Issue										~					
Date										^					
Estimated															Υ
Implementation Date															^

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

February 7, 2019: Issued initial notification.

April 26, 2019: Issued final notification. Attached the Qualification Report. Provided on May 26,

2019

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-24CGNQ027_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

PIC12F683-E/MD

PIC12F683-I/MD

PIC12F683T-E/MD

PIC12F683T-I/MD

PIC12HV609-E/MD

PIC12HV609-I/MD

PIC12HV609T-I/MD

PIC12HV615-E/MD

PIC12HV615-I/MD

PIC12HV615T-I/MD

PIC12F609-E/MD

PIC12F609-I/MD

PIC12F609T-I/MD

PIC12F615-E/MD

PIC12F615-H/MD

PIC12F615-I/MD

PIC12F615T-I/MD

PIC12F615T-I/MD029

PIC12F629-E/MD

PIC12F629-I/MD

PIC12F629T-E/MD

PIC12F629T-I/MD

PIC12F635-I/MD

PIC12F635T-I/MD

PIC12F635T-I/MD070

PIC12F635T-I/MD073

PIC12F675-E/MD

PIC12F675-I/MD

PIC12F675-I/MD176

PIC12F675T-E/MD

PIC12F675T-I/MD

Date: Thursday, April 25, 2019